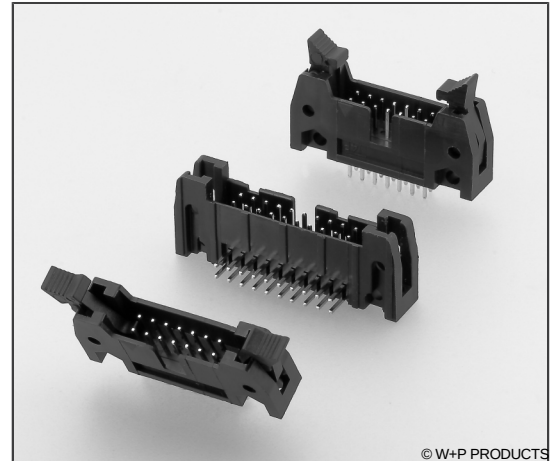


Technische Daten / Technical Data

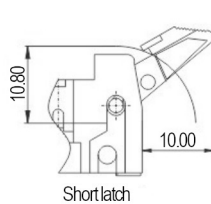
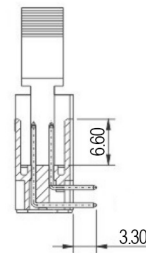
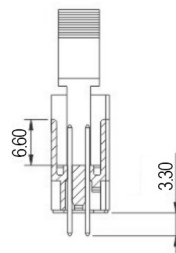
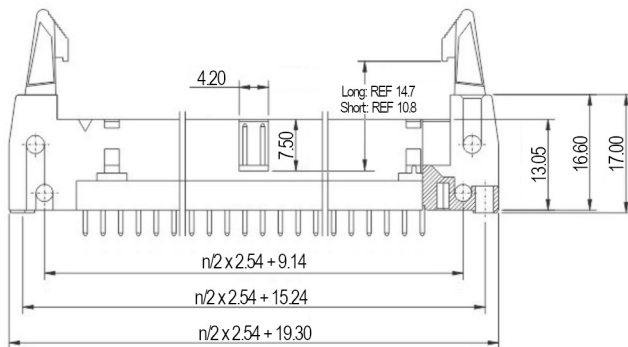
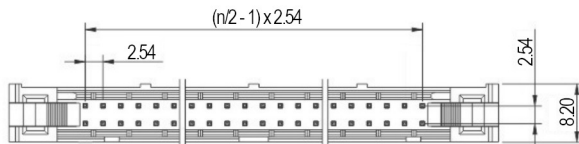
Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Vierkantstift 0,635mm, Kupferlegierung <i>Square pin 0.635mm, copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni <i>Acc. to options (see below), over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ <i>< 20 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 5 GΩ <i>> 5 GΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	1000 V AC <i>1000 V AC</i>
Nennspannung <i>Voltage Rating</i>	250 V AC <i>250 V AC</i>
Nennstrom <i>Current Rating</i>	3 A <i>3 A</i>
Temperaturbereich <i>Temperature Range</i>	-55 °C ... +105 °C <i>-55 °C ... +105 °C</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>



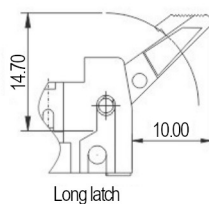
© W+P PRODUCTS

Passende Gegenstecker:
Compatible Connectors:

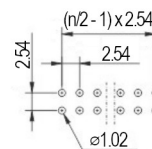
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Short latch



Long latch



PCB Layout

Series	Contacts*	Type*	Latches*	Plating*	Colour (Optional)*	Material
138	26	1	00	60	..	HT
	10/14/16/20/ 24/26/30/34/ 40/44/50/60/ 64	1 Gerade Straight 2 Gewinkelt Right-angled	00 Ohne Hebel W/o latches 10 Kurze Hebel Short latches 20 Lange Hebel für Gegenstecker mit Zugentlastung Long Latches for mating connectors with strain relief	00 Vergoldet Gold plated 60 Sel. Au/Sn Duplex Plating	[] Standard: schwarz Standard: black 6 Grau Grey	HT Hi-Temp (Reflow Soldering)

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.

* This is an **order example** -
please replace by your specifications.

Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

